

11/8/04

11-12-2004

FORM PTO-1595
(Rev. 6-93)
OMB No. 0651-0011 (exp. 4/94)



U.S. Department of Commerce
Patent and Trademark Office

102879946

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original document or copy thereof.

1. Name of conveying party(ies): Date
 Optonics, Inc. October 27, 2004

Additional name(s) of conveying party(ies) attached? Yes No

3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other _____ Execution Date:

2. Name and address of receiving party(ies):
 Name: Credence, Inc.
 Internal Address:
 Street Address: 1421 California Circle, 95035
 City: Milpitas State: CA Zip: 95035

Additional name(s) & address(es) attached? Yes No

4. Application number(s) or registration number(s):
 If this document is being filed together with a new application, the execution date of the application is: (Date of Filing)

A. Patent Application No.(s)
 B. Patent No. 6,594,086
 Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:
 Name: Joseph Bach
 Internal Address: JBPatents.com
 Street Address: 17460 Lakeview Drive
 City: Morgan Hill State: CA Zip: 95037

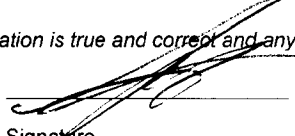
6. Total number of applications and patents involved: 1

7. Total fee (37 C.F.R. 3.41)----- \$ 40.00
 Enclosed
 Authorized to be charged to deposit account

8. Deposit account number:

DO NOT USE THIS SPACE

9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

JOSEPH BACH Reg No 37,771  November 1, 2004
 Name of Person Signing Signature Date

Total number of pages including cover sheet, attachments and document: 4

Mail documents to be recorded with required cover sheet information to:
 Commissioner of Patents & Trademarks, Box Assignments
 Washington, D.C. 20231

11/10/2004 MSETACHE 00000033 6594086

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ASSIGNMENT OF PATENTS AND PATENT APPLICATIONS

WHEREAS, Optonics, Inc., hereinafter called "ASSIGNOR", a California corporation having its principal place of business at 2593 Coast Avenue, Suite 100, Mountain View, California 94043, is the assignee of certain patents and patent applications listed in Appendix A attached herewith and comprising two pages.

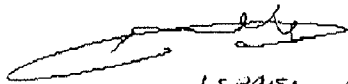
AND WHEREAS Credence Systems Corporation, a Delaware corporation, having its principal place of business at 1421 California Circle Milpitas, California 95035, together with any successors, legal representatives or assigns thereof, called "ASSIGNEE" wants to acquire the entire right, title and interest in and to said patents and patent applications.

NOW, THEREFORE, in consideration of the sum of \$1.00, the receipt thereof is hereby acknowledged, and other good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR have sold, assigned, transferred and set over, and do hereby sell, assign, transfer and set over to ASSIGNEE the entire right, title and interest in and to said improvements, and said application and all divisions and continuations thereof, and all United States Letters Patents which may be granted thereon and all reissues, reexaminations and extensions thereof, and all priority rights under all available International Agreements, Treaties and Conventions for the protection of Intellectual property in its various forms in every participating country, and all applications for patents (including related rights such as utility-model registrations, inventor's certificates, and the like) heretofore or hereafter filed for said improvements in any foreign countries, and all patents (including all continuations, divisions, extensions, renewals, substitutes, and reissues thereof) granted for said improvements in any foreign countries; and we hereby authorize and request the United States Commissioner of Patents and Trademarks, and any officials of foreign countries whose duty it is to issue patents on applications as aforesaid, to issue all patents for said improvements to ASSIGNEE in accordance with the terms of this Assignment.

AND ASSIGNOR HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

IN TESTIMONY WHEREOF, I hereunto set my hand this 7 day of October, 2004

Signature of ASSIGNOR:



15/10/04 NIV

For Optonics Inc.

By: Israel Niv

Title: President and CEO

STATE OF CALIFORNIA

APPENDIX A	Country	Title	Patent No.	1 of 2
Application No.				
09/095,548	United States	Time Resolved Non-Invasive Diagnostics System	6,521,275	
10/457,988	United States	Time Resolved Non-Invasive Diagnostics System		
PCT/US01/38431	Patent Cooperation Treaty	Time Resolved Non-Invasive Diagnostics System		
2797156.3	European Patent Convention	Time Resolved Non-Invasive Diagnostics System		
2003-547980	Japan	Time Resolved Non-Invasive Diagnostics System		
2004-7007251	South Korea	Time Resolved Non-Invasive Diagnostics System		
91134678	Taiwan	Time Resolved Non-Invasive Diagnostics System		
10/052,011	United States	Bi-Convex Solid Immersion Lens	6,594,086	
10/440,866	United States	Bi-Convex Solid Immersion Lens	6,778,327	
10/883,542	United States	Bi-Convex Solid Immersion Lens		
PCT/US02/39538	Patent Cooperation Treaty	Bi-Convex Solid Immersion Lens		
2004-7007230	South Korea	Bi-Convex Solid Immersion Lens		
2822785.9	China P.R.	Bi-Convex Solid Immersion Lens		
91137365	Taiwan	Bi-Convex Solid Immersion Lens		
10/379,950	United States	Universal Platform for Integrated Circuit Analysis		
10/255,345	United States	Solid Immersion Lens Landing System		
10/930,454	United States	Solid Immersion Lens Landing System		
10/294,434	United States	Avalanche Photo Diode for Photon Counting Applications	6,720,568	
10/721,915	United States	Avalanche Photo Diode for Photon Counting Applications and Method Thereof	6,797,561	
91133774	Taiwan	Avalanche Photo Diode for Photon Counting Applications	201324	
PCT/US02/37366	Patent Cooperation Treaty	Avalanche Photo Diode for Photon Counting Applications and Method Thereof		
2804016	European Patent Convention	Avalanche Photo Diode for Photon Counting Applications and Method Thereof		
2003-648319	Japan	Avalanche Photo Diode for Photon Counting Applications and Method Thereof		
91133774	Taiwan	Avalanche Photo Diode for Photon Counting Applications and Method Thereof		
2820685.1	China P.R.	Avalanche Photo Diode for Photon Counting Applications and Method Thereof		
2004-7007361	South Korea	Avalanche Photo Diode for Photon Counting Applications and Method Thereof		
10/222,107	United States	Spray Cooling Thermal Management System and Method for Semiconductor Probing, Diagnostics, and Failure Analysis		
60/385,524	United States	Intra Chip Signal Communication System for IC Devices and Method Using Hot Electron Photoemission		
10/379,925	United States	Spray Cooling and Transparent Cooling Plate Thermal Management System		
PCT/US03/036547	Patent Cooperation Treaty	Spray Cooling and Transparent Cooling Plate Thermal Management System		

APPENDIX A	Application No.	Country	Title	Patent No.	2 of 2
	92132829	Taiwan	Spray Cooling and Transparent Cooling Plate Thermal Management System		
	10/613,593	United States	Time Resolved Emission Spectra Analysis System		
	10/408,988	United States	System and Method for Calibration of Testing Equipment using Device Photoemission		
	PCT/US04/010728	Patent Cooperation Treaty	System and Method for Calibration of Testing Equipment using Device Photoemission		
	93109727	Taiwan	System and Method for Calibration of Testing Equipment using Device Photoemission		
	10/719,880	United States	Shutter Blade Position Detection		
	10/845,013	United States	Beacon Circuit for Photo Emission Voltage Analysis		
	10/872,595	United States	Integrated APD and Lens Assembly		
	10/912,896	United States	Light Beam Apparatus and Method for Orthogonal Alignment of Specimen		
	10/229,181	United States	Apparatus and Method for Dynamic Diagnostic Testing of Integrated Circuits		
	92101517	Taiwan	Apparatus and Method for Dynamic Diagnostic Testing of Integrated Circuits		
	03713326.1-1236	European Patent Convention	Apparatus and Method for Dynamic Diagnostic Testing of Integrated Circuits		
	03802724.D.	China P.R.	Apparatus and Method for Dynamic Diagnostic Testing of Integrated Circuits		
	2003-566568	Japan	Apparatus and Method for Dynamic Diagnostic Testing of Integrated Circuits		
	2004-7011746	South Korea	Apparatus and Method for Dynamic Diagnostic Testing of Integrated Circuits		
	10/341,721	United States	Apparatus and Method for Measuring Characteristics of Dynamic Electrical Signals in Integrated Circuits		